



Product Listing and Typical Properties

Resin	Product Description	Tg	Type IPC-4101	UL-94	Fabric	Comments
<b>Polyimide Products</b>						
33N	Kerimid 701 (V0) Polyimide	250°C	GIL /40; 41	V0	E	Maximum Flame Retardance
35N	Kerimid 701 (V1) Polyimide	250°C	GIL /40; 41	V1	E	Reduced Cure Time
85N	Polyimide - Unmodified	250°C	GIL /40; 41	HB	E	Maximum Thermal Stability
84N	Multifilm Hole-Fill Prepreg	250°C	GIL /40; 41	N/A	E	Filled 85N
EP2	Enhanced Polyimide	250°C	GIL /40; 41	V0	E	Beta Filled, High Peel
37N	Low-Flow Polyimide Prepreg	200°C	GIJ /42	N/A	E	Rigid Flex
38N	Low-Flow Polyimide Prepreg	200°C	GU /42	N/A	E	Enhanced Rheology, Rigid Flex
HF-50	Hole-Fill Compound	250°C	N/A	N/A	None	Fill Clearance Holes

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<b>Epoxy Products</b>						
45N	Multifunctional Epoxy	170°C	GFG /24	V0	E	High Layer Count MLB's
44N	"Multifilm" Hole-Fill Prepreg	170°C	GFG /24	V0	E	Filled 45N
47N	Low-Flow Modified Tetrafunctional Epoxy Prepreg	130°C	GFN /21	V0	E	Rigid Flex, Heat Sinks
49N	Low-Flow Multifunctional Prepreg	170°C	GFG /24	V0	E	Rigid Flex, Heat Sinks
51N	Low-Flow Lead-Free	170°C	GFG /124	V0	E	Lead Free Soldering

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<b>Thermally Conductive Products</b>						
91ML	Thermally Conductive	170°C	GFG /98	V0	E	1.0 W/m-K Multilayerable System Halogen Free
92ML	Thermally Conductive	170°C	GFG /98	V0	G	2 W/m-K Multilayer Halogen Free
99ML	Thermally Conductive	170°C	GFG /98	V0	E	1.1 W/m-K Heat Sink Bonding Ply

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<b>Controlled Thermal Expansion</b>						
45NK	Multifunctional Epoxy/Kevlar®	170°C	AFN /50	N/A	K	CTE = 4-7 ppm/°C
55NT	Multifunctional Epoxy/Thermount®	170°C	BFG /55	V0	B	CTE = 7-8 ppm/°C
85NT	Polyimide/Thermount®	240°C	BIL /53	N/A	B	CTE = 7-8 ppm/°C
85N	Copper-Invar-Copper Clad Polyimide	250°C	GIL /40; 41	HB	E	CTE = 9-12 ppm/°C
45N	CIC Clad Multifunctional Epoxy	170°C	GFG /24	V0	E	CTE = 9-12 ppm/°C
35NQ	Polyimide Quartz	250°C	QIL /60	N/A	Q	CTE = 9-12 ppm/°C

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<b>HDI/Microvia/CAF Resistance</b>						
55LM	Low Moisture Regain Thermount®	160°C	GFG /55	V0	B	Moisture Uptake equivalent to FR-4
55ST	Multifunctional Epoxy/Thermount®	175°C	BFG /55	V0	B	CTE = 10-12 ppm/°C 10 lb/in copper peel strength

<b>Specialty Foils</b>						
Electrodeposited, High Temperature Elongation, Copper Foil						
Double Treat and Drum Side Treated Copper Foil						
5 and 9 Micron Copper Foil (Fine Line Designs)						
Ohmega-Ply® Resistive Clad Copper Foil (Etched Planar Resistors)						

Kevlar® and Thermount® are tradenames of the DuPont Company  
Fabric Types: E = E-Glass, Q = Quartz Fabric, K = Kevlar®, B = Thermount®



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